

Tin

SLOTOTIN SBT 1730

Strongly acidic tin electrolyte for the deposition of semi-bright coatings even in the low current density range. Suitable for geometrically complex components. The grain size is between 0.8 and 2.0 µm. Plated layers are compatible with all lead-free solder alloys.

APPLICATION

- Electronics (lead frames, connectors, etc.)

PROCESS

- Rack- and barrel plating lines
- Without sulphuric acid
- Operation in the low temperature range possible
- Can be used as bright tin process by adjusting the additives

BENEFITS

- Very low carbon incorporation, approx. 0,05 % by weight
- Very good solderability, even after aging
- Meets RoHS Directive 2011/65/EU

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

